Surface Mount - 7000 W - TO-263











Maximum Ratings and Thermal Characteristics (T_A = 25 °C unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak Pulse Power Dissipation 1. 10 ms/150 ms test waveform	P _{PPM}	1400	W
2. 10 µs/1000 µs test waveform	PPIVI	7000	W
Power Dissipation on Infinite Heatsink at $T_c = 25$ °C	P _D	9	W
Maximum Instantaneous Forward Voltage at 100 A for Un-idirectional Only	V _F	1.8	V
Peak Forward Surge Current 8.3 m Single Half Sine-wave	I _{FSM}	650	А
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 to 150	°C
Typical Thermal Resistance Junction to Case	$R_{\theta JC}$	1.3	°C/W

Description

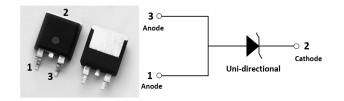
The SLD263 uni-directional TVS diode series is housed in a TO-263 package with lead modifications. It is designed to protect sensitive electronics against ESD, EFT, 10/1000 surge events and inductive load switching voltage transient events for severe automotive load dump applications.

Features & Benefits

- AEC-Q101 qualified and PPAP UL recognized compound capable
- Meet ISO7637-2 5a/5b protection, ISO16750 and JASO D-001 load dump test (refer to APP note for details)
- $V_{BR} @ T_{J} = V_{RR} @ 25 °C \times (1 + \alpha T)$ $\times (T_1 - 25))(\alpha T: temperature)$ coefficient, typical value is 0.1
- Glass passivated chip junction in modified TO-263 package
- ESD protection of data lines in accordance with IEC 61000-4-2, 30 kV(Air), 30 kV (Contact)
- EFT protection of data lines in accordance with IEC 61000-
- Fast response time: typically less than 1.0 ps from 0 volts to V_{BR} min
- Excellent clamping capability
- Low incremental surge resistance

- meeting flammability rating UL94 V-0
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- For surface mounted applications to optimize board space
- Low profile package
- High temperature reflow soldering guaranteed: 260 °C/10 sec at terminals
- Matte tin lead-free plated
- Halogen free and RoHS compliant
- Pb-free E3 means 2nd level interconnect is pb-free and the terminal finish material is tin (Sn) (IPC/JEDEC J-STD-609A.01)

Functional Diagram



Applications

Designed to protect sensitive electronics from:

- Inductive load switching
- Alternator load dump



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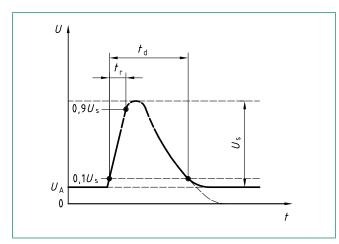
Electrical Characteristics ($T_A = 25$ °C unless otherwise noted)

Part Number Marking (Uni)	Breakdown Voltage V _{BR} @ I _T (V)	Test Current I _T	Reverse Stand off Voltage V _R	Maximum Reverse Leakage I _R @ V _R	T _J = 150 °C Max. Reverse Leakage	Maximum Peak Pulse Surge Current I	Maximum Clamping Voltage V _c @ I _{pp}		
(OIII)		Min	Max	(mA)	(V)	ι _R ω ι _R (μΑ)	Ι _R @ V _R (μΑ)	(A)	(V)
SLD263-22A	263-22A	24.4	26.9	5	22	2	50	197	35.5
SLD263-24A	263-24A	26.7	29.5	5	24	2	50	180	38.9

Notes:

- 1. $V_{_{BR}}$ measured after $I_{_{T}}$ applied for 300 $\mu s,\,I_{_{T}}\!\!=\!square$ wave pulse or equivalent.
- 2. Surge current waveform per 10 $\mu s/1000~\mu s$ exponential wave and derated per Fig. 2
- 3. All terms and symbols are consistent with ANSI/IEEE C62.35.

Load Dump Test Wave Form



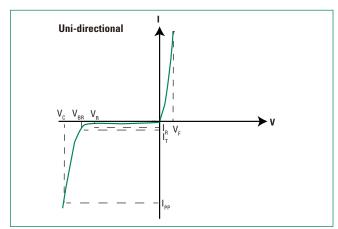
Parameter	12 V system	24 V system	
U_s	65 V to 87 V	123 V to 174 V	
R_{i}	0.5 Ω to 4 Ω	1 Ω to 8 Ω	
t _d	40 ms to 400 ms	100 ms to 350 ms	
t _r	(10 ⁰ ₋₅)ms		

Note: LF use td = 400 ms for 12 V system test; td = 350 ms for 24 V system



Surface Mount - 7000 W - T0-263

I-V Curve Characteristics



- P_{PPM} Peak Pulse Power Dissipation ($I_{PP} \times V_c$) -- Max power dissipation
- ${f V_{\scriptscriptstyle R}}$ Stand-off Voltage Maximum voltage that can be applied to the TVS without operation
- ${f V}_{\tt BR}$ **Breakdown Voltage** Maximum voltage that flows though the TVS at a specified test current (I,)
- $m V_c$ Clamping Voltage Peak voltage measured across the TVS at a specified I_{PPM} (peak impulse current)
- V, Forward Voltage Drop for Uni-directional

Ratings and Characteristic Curves ($T_A = 25$ °C unless otherwise noted)

Figure 1 - Peak Pulse Power Rating Curve

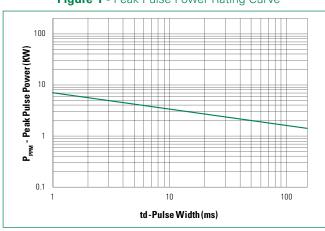


Figure 2 - Peak Pulse Power Derating Curve

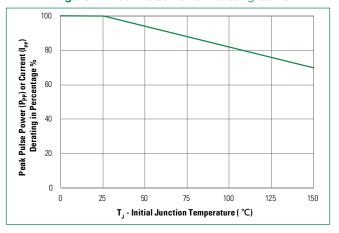


Figure 3 - Typical Transient Thermal Impedance

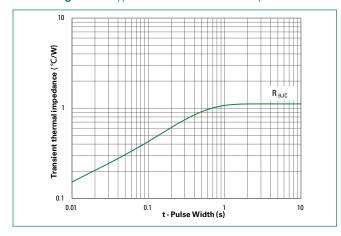
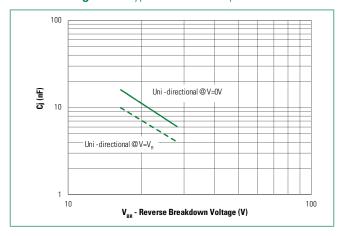


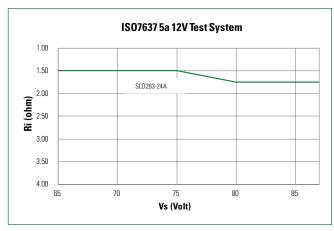
Figure 4 - Typical Junction Capacitance





SLD263 Uni-directional Series Surface Mount - 7000 W - TO-263

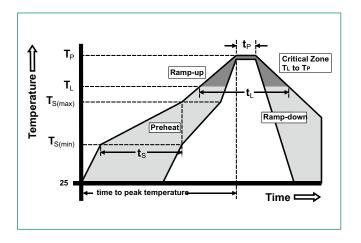
Figure 5 - Typical SOA Chart



Note: SOA (Safe Operation Area) refer to the area which below the curve line and refer to APP note for details.

Soldering Parameters

Reflow Cond	Lead-free assembly	
	-Temperature Min (T _{s(min)})	150 °C
Pre Heat	-Temperature Max (T _{s(max)})	200 °C
	-Time (min to max) (t _s)	60 – 120 seconds
Average Ran Peak	np Up Rate (Liquidus Temp (T _L) to	3 °C/second max
$T_{\text{S(max)}}$ to T_{L} -	3 °C/second max	
Reflow	-Temperature (T _L) (Liquidus)	217 °C
	-Time (min to max) (t _L)	60 – 150 seconds
Peak Temper	260 ^{+0/-5} °C	
Time Within	30 seconds max	
Ramp-down	6 °C/second max	
Time 25°C to	8 minutes max	
Do Not Exce	ed	260 °C





Surface Mount - 7000 W - TO-263

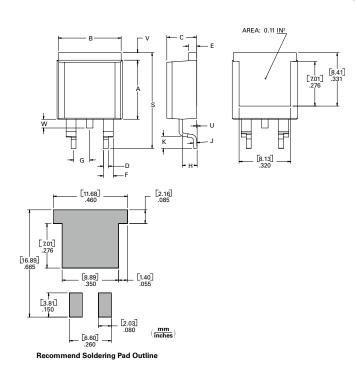
Physical Specifications

Terminal Finish	100 % matte tin-plated
Body Material	UL recognized compound meeting flammability classification UL94 V-0
Lead Material	Copper alloy

Environmental Specifications

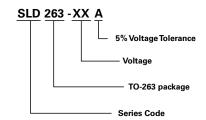
High Temperature Storage	JESD22-A103
HTRB	JESD22-A108
Temperature Cycling	JESD22-A104
MSL	JEDEC-J-STD-020, LEVEL 1
H3TRB	JESD22-A101
RSH	JESD22-A111

Dimensions

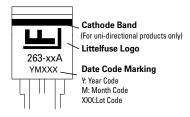


Dimensions	Inc	hes	Millimeters		
Dimensions	Min	Max	Min	Max	
А	0.36	0.37	9.14	9.4	
В	0.38	0.42	9.65	10.67	
С	0.178	0.188	4.52	4.78	
D	0.025	0.035	0.64	0.89	
E	0.045	0.06	1.14	1.52	
F	0.06	0.075	1.52	1.91	
G	0.095	0.105	2.41	2.67	
Н	0.092	0.102	2.34	2.59	
J	0.018	0.024	0.46	0.61	
K	0.09	0.11	2.29	2.79	
S	0.59	0.625	14.99	15.88	
V	0.035	0.045	0.89	1.14	
U	0.002	0.01	0.05	0.25	
W	0.04	0.07	1.016	1.78	

Part Numbering System



Part Marking System





Surface Mount - 7000 W - TO-263

Packaging

Part Number	Component Package	Quantity	Packaging Option
SLD263-xxA	TO-263	500	Embossed Carrier

TO-263 Embossed Carrier Reel Pack (RP) Specifications

Meets all EIA-481-2 Standards

